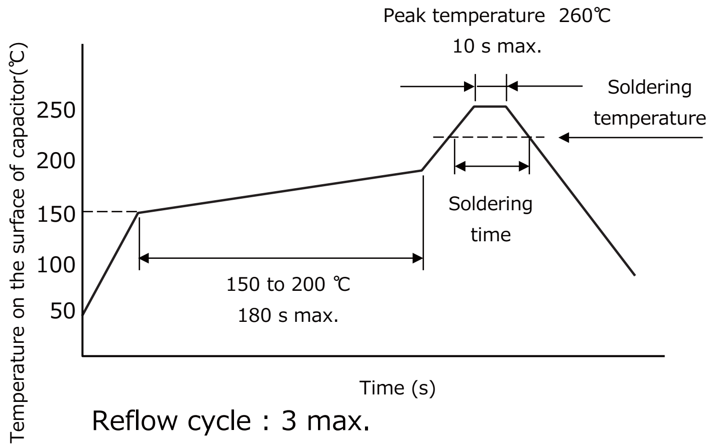
Mounting specification

● Recommendable reflow soldering



Reflow cycle : 3 max.

Soldering temperature and soldering time

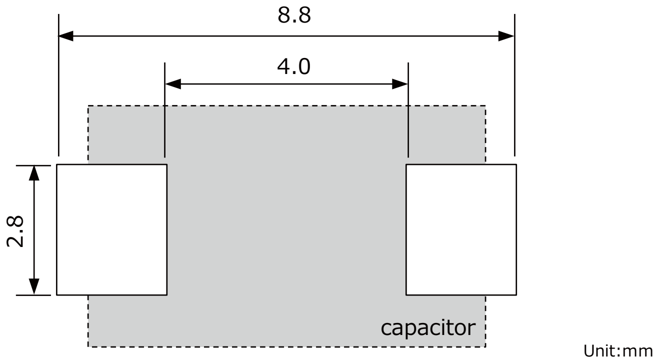
Temperature	Time
≧ 255℃	30 s max.
≧ 230℃	130 s max.
≧ 217℃	150 s max.

SP-Cap recommended
profile condition of the
IPC/J-STD-020D standard

● Typical land pattern

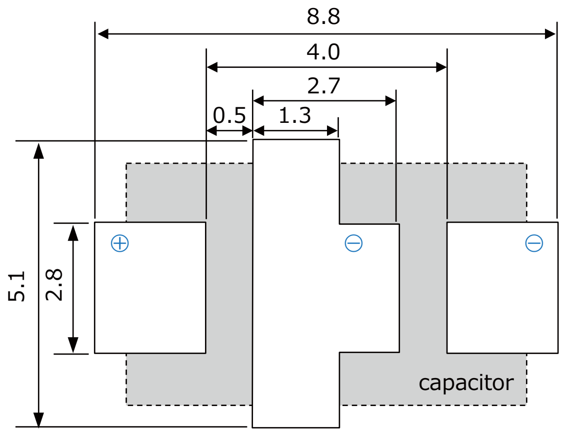
☐ 2-terminals

For standard terminal（C＊, S＊, G＊, HX series）



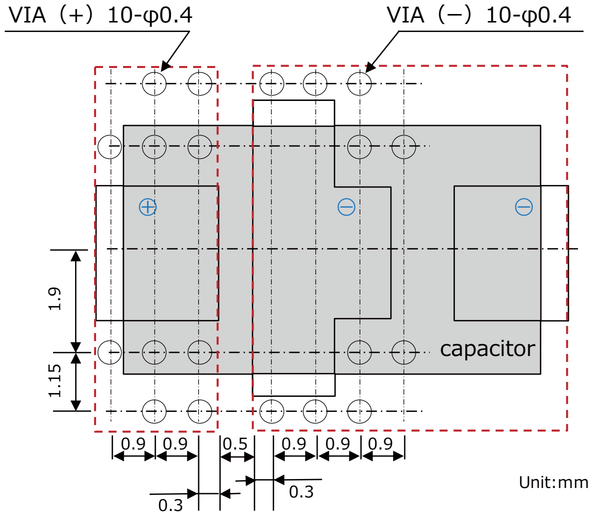
☐ 3-terminals

For low ESL terminal（L＊, GX-L series）



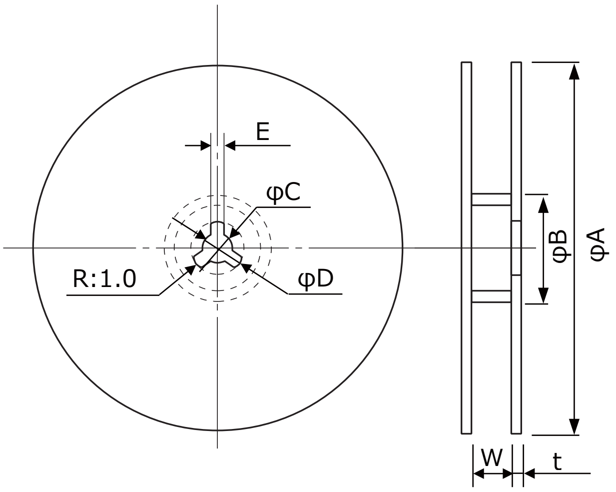
〈VIA〉

For low ESL terminal（L＊, GX-L series）



Packaging specifications

- Reel dimensions

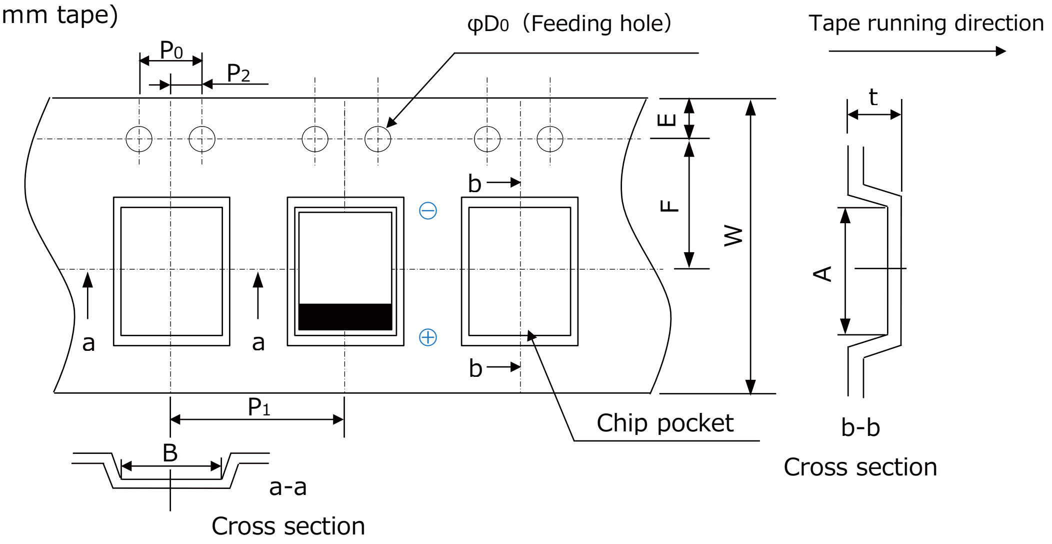


Unit:mm

Reel	φA	φB	φC	φD	E	W	t
φ330	330	80	13±0.5	21±0.8	2±0.5	14	3
φ180	180	60	13±0.5	21±0.8	2±0.5	14	3

- Embossed taping

(12mm tape)

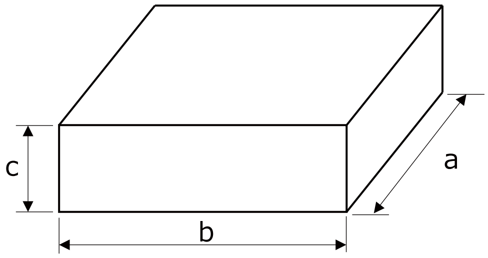


Unit:mm

A	B	W	F	E	P_1
7.6±0.2	4.5±0.2	12±0.3	5.5±0.1	1.75±0.1	8.0±0.1

P_2	P_0	φD_0	Upper row : Product height / Lower berth : t		
			to 1.1	1.4 to 1.9	2.8
2.0±0.1	4.0±0.1	$1.5^{+0.1}_{0}$	1.5±0.2	2.4±0.2	3.5±0.2

- Packaging box dimensions



Unit:mm

Reel	a	b	c
φ330	400 max.	400 max.	135 max.
φ180	320 max.	240 max.	135 max.